

STGW12NB60H

N-CHANNEL 12A - 600V TO-247 PowerMESHTM IGBT

PRELIMINARY DATA

TYPE	V _{CES}	V _{CE(sat)}	Ic
STGW12NB60H	600 V	< 2.8 V	12 A

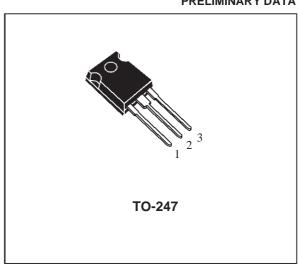
- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW ON-VOLTAGE DROP (VCESAT)
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- VERY HIGH FREQUENCY OPERATION
- OFF LOSSES INCLUDE TAIL CURRENT

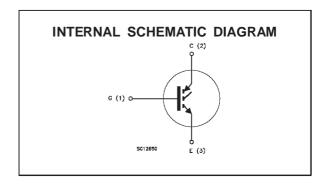
DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESHTM IGBTs, with outstanding perfomances. The suffix "H" identifies a family optimized to achieve very low switching times for high frequency applications (<120kHz).

APPLICATIONS

- HIGH FREQUENCY MOTOR CONTROLS
- SMPS AND PFC IN BOTH HARD SWITCH AND RESONANT TOPOLOGIES





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CES}	Collector-Emitter Voltage (V _{GS} = 0)	600	V
V _{ECR}	Emitter-Collector Voltage	20	V
V_{GE}	Gate-Emitter Voltage	± 20	V
Ic	Collector Current (continuous) at T _c = 25 °C	24	А
Ic	Collector Current (continuous) at T _c = 100 °C	12	А
I _{CM} (•)	Collector Current (pulsed)	96	А
P _{tot}	Total Dissipation at T _c = 25 °C	120	W
	Derating Factor	0.96	W/°C
T _{stg}	Storage Temperature	-65 to 150	°C
T _j	Max. Operating Junction Temperature	150	°C

(•) Pulse width limited by safe operating area

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THERMAL DATA

Γ	R _{thj-case}	Thermal	Resistance	Junction-case	Max	1.04	°C/W
	R _{thj-amb}	Thermal	Resistance	Junction-ambient	Max	30	oC/W
	R_{thc-h}	Thermal	Resistance	Case-heatsink	Тур	0.1	°C/W

ELECTRICAL CHARACTERISTICS ($T_j = 25$ $^{\circ}C$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{BR(CES)}	Collector-Emitter Breakdown Voltage	$I_C = 250 \ \mu A$ $V_{GE} = 0$	600			V
I _{CES}	Collector cut-off (V _{GE} = 0)	$V_{CE} = Max Rating$ $T_j = 25 ^{\circ}C$ $V_{CE} = Max Rating$ $T_j = 125 ^{\circ}C$			10 100	μΑ μΑ
I _{GES}	Gate-Emitter Leakage Current (V _{CE} = 0)	$V_{GE} = \pm 20 \text{ V}$ $V_{CE} = 0$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$V_{\text{GE(th)}}$	Gate Threshold Voltage	$V_{CE} = V_{GE}$ $I_C = 250 \mu A$	3		5	V
V _{CE} (SAT)		$V_{GE} = 15 \text{ V}$ $I_{C} = 12 \text{ A}$ $V_{GE} = 15 \text{ V}$ $I_{C} = 12 \text{ A}$ $T_{j} = 125 ^{\circ}\text{C}$		2.0 1.7	2.8	V

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g fs	Forward Transconductance	V _{CE} =25 V I _C = 12 A		9.5		S
C _{ies} C _{oes} C _{res}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{CE} = 25 V f = 1 MHz V _{GE} = 0		950 120 27		pF pF pF
Q _G Q _{GE} Q _{GC}	Total Gate Charge Gate-Emitter Charge Gate-Collector Charge	V _{CE} = 480 V I _C = 12 A V _{GE} = 15 V		68 10 30		nC nC nC
I _{CL}	Latching Current	$V_{clamp} = 480$	48			А

SWITCHING ON

Symbol	Parameter	Test Conditions			Тур.	Max.	Unit
t _{d(on)}	Delay Time Rise Time	V _{CC} = 480 V V _{GE} = 15 V	$I_C = 12 A$ $R_G = 10\Omega$		5 46		ns ns
(di/dt) _{on}	Turn-on Current Slope	$V_{CC} = 480 \text{ V}$ $R_G = 10 \Omega$	I _C = 12 A V _{GE} = 15 V		1000		A/μs
Eon	Turn-on Switching Losses	T _j = 125 °C			290		μJ

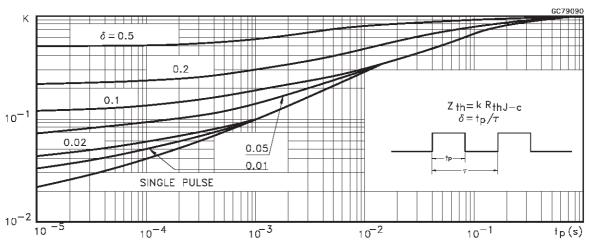
ELECTRICAL CHARACTERISTICS (continued)

SWITCHING OFF

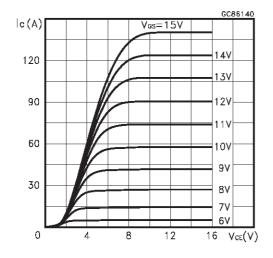
Symbol	Parameter	Test Co	nditions	Min.	Тур.	Max.	Unit
t_c $t_r(v_{off})$	Cross-Over Time Off Voltage Rise Time	$V_{CC} = 480 \text{ V}$ $R_{GE} = 10 \Omega$	$I_C = 12 A$ $V_{GE} = 15 V$		150 27		ns ns
$t_{d(off)}$ t_{f} $E_{off}(**)$ E_{ts}	Delay Time Fall Time Turn-off Switching Loss Total Switching Loss				76 92 0.21 0.49		ns ns mJ mJ
t _c t _r (v _{off}) t _d (off) t _f E _{off} (**) E _{ts}	Cross-Over Time Off Voltage Rise Time Delay Time Fall Time Turn-off Switching Loss Total Switching Loss	$V_{CC} = 480 \text{ V}$ $R_{GE} = 10 \Omega$ $T_{j} = 125 ^{\circ}\text{C}$	I _C = 12 A V _{GE} = 15 V		230 76 95 200 0.45 0.74		ns ns ns ns mJ mJ

^(•) Pulse width limited by max. junction temperature
(*) Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %
(**)Losses Include Also The Tail (Jedec Standardization)

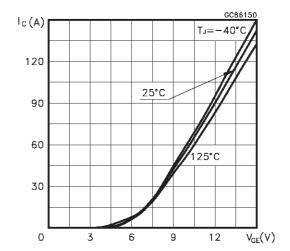
Thermal Impedance



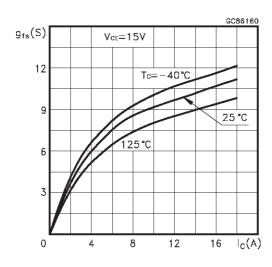
Output Characteristics



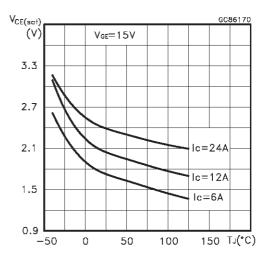
Transfer Characteristics



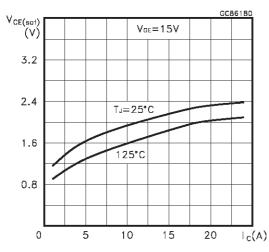
Transconductance



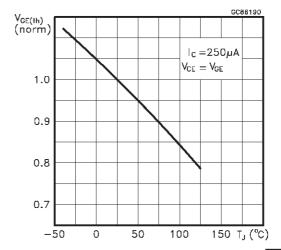
Collector-Emitter On Voltage vs Temperature



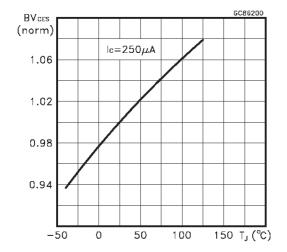
Collector-Emitter On Voltage vs Collector Current



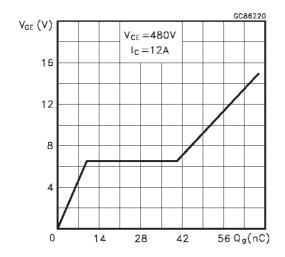
Gate Threshold vs Temperature



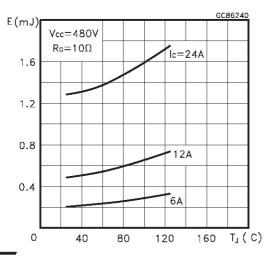
Normalized Breakdown Voltage vs Temperature



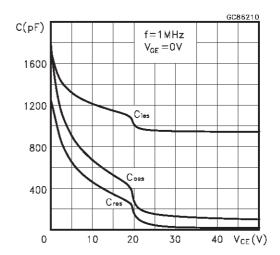
Gate Charge vs Gate-Emitter Voltage



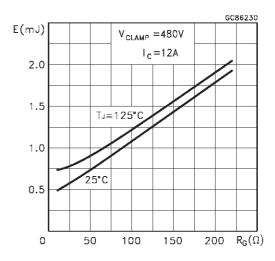
Total Switching Losses vs Temperature



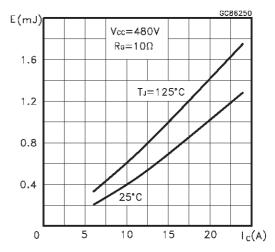
Capacitance Variations



Total Switching Losses vs Gate Resistance



Total Switching Losses vs Collector Current



Switching Off Safe Operating Area

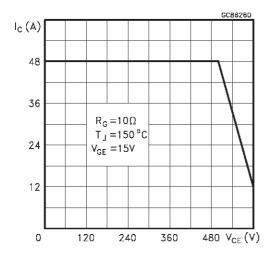


Fig. 1: Gate Charge test Circuit

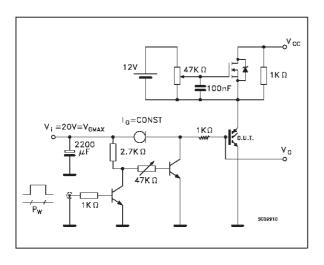


Fig. 2: Test Circuit For Inductive Load Switching

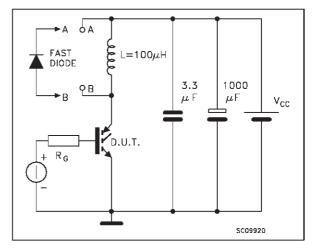
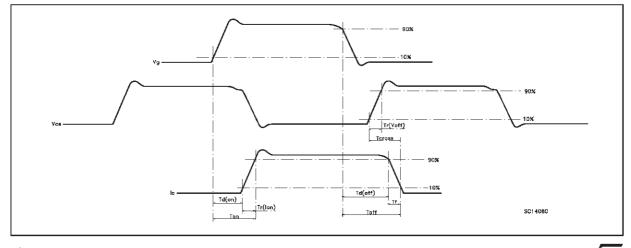
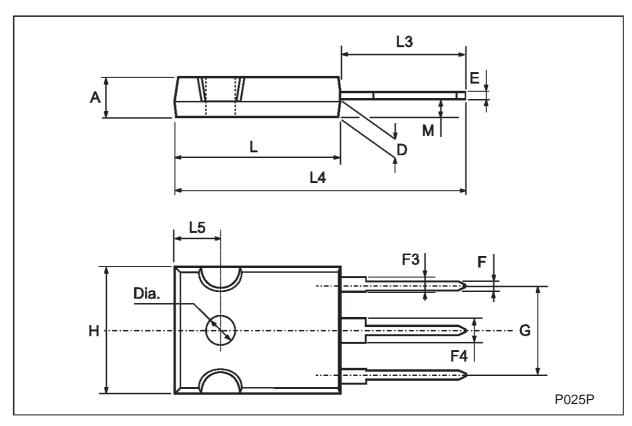


Fig. 3: Switching Waveforms



TO-247 MECHANICAL DATA

DIM.		mm				
DIWI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.7		5.3	0.185		0.209
D	2.2		2.6	0.087		0.102
E	0.4		0.8	0.016		0.031
F	1		1.4	0.039		0.055
F3	2		2.4	0.079		0.094
F4	3		3.4	0.118		0.134
G		10.9			0.429	
Н	15.3		15.9	0.602		0.626
L	19.7		20.3	0.776		0.779
L3	14.2		14.8	0.559		0.582
L4		34.6			1.362	
L5		5.5			0.217	
М	2		3	0.079		0.118



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